

**B.****AMENDMENTS TO THE SPECIFICATION**

This invention relates to a methods of connecting and/or supporting electronic devices. It is an improved method of forming the metal bumps or protuberances on the surface of a substrate. The metal bumps or protuberances formed according to the method of this invention are capable of providing electrical connections and physical support for the electronic devices. Electronic devices include active and passive components, semiconductor dice and electromechanical devices. Electromechanical devices include relays, shutters, solenoids, accelerators, microelectromechanical systems (MEMS) and the like. MEMS include, but are not limited to, micro flowmeters, miniature tuning forks, optical shutters, micropumps, miniature metering valves, miniature electromechanical relays, sensors, air-bag sensors and solenoids.